Product Qualification Report

BCR402W

Linear LED Driver IC

Description

This product qualification report describes the characteristics of the product with respect to quality and reliability.

The qualification sample selection was done on production lots which were manufactured and tested on standard production processes and meet the defined requirements.

The qualification test results of those products as outlined in this document are based on **AEC Q101** for target applications and may reference existing qualification results of similar products. Such referencing is justified by the structural similarity of the products.

Qualification Assessment

Qualified acc. **AEC Q101** and assessed as PASS

For further information about comparable products, please contact the nearest Infineon Technologies office (www.infineon.com).

BCR402W **qualified in 2007**
PG-SOT343-4
MSL: 1, 260°C

Electrical Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/ss	Fail/Qty	Result
Electrical Distribution	ED	-55°C, +25°C, +150°C		1 x 40	0 / 40	PASS
High Humidity High Temperature Reverse Bias JESD22 A101	H3TRB	Ta=85°C, RH=85%	1000 h	6 x 40	0 / 240	PASS
High Temperature Reverse Bias JESD22 A108	HTRB	Ta=150°C	1000 h	6 x 40	0 / 240	PASS
ESD Human Body Model JESD22 A114	HBM	Class 1B 500 to < 1000V		1 x 12	0 / 12	PASS
ESD Machine Model JESD22 A115	MM	Class B 200 to < 400V		1 x 12	0 / 12	PASS

Environmental Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Preconditioning J-STD020 / JESD22 A113	PC	Soak acc.MSL1, 3x reflow, 260°C		18 x 60	0 / 1080	PASS
Temperature Cycling* JESD22 A104	TC*	-55°C to +150°C	1000 cyc	12 x 60	0 / 720	PASS
Autoclave* JESD22 A102	AC*	Ta=121°C, RH=100%	96 h	6 x 60	0 / 360	PASS

Mechanical Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Destructive Physical Analysis	DPA	Random samples from H3TRB & TC		6 x 4	0 / 24	PASS
Physical Dimensions JESD B-100	PD			1 x 30	0 / 30	PASS
Resistance to Solder Heat JESD B-106	RTSH	Solder bath Ts=260°C, dip 3 x 10 sec		1 x 30	0 / 30	PASS
Solderability J-STD-002	SD			1 x 10	0 / 10	PASS

Notes:

* For SMD devices reliability stress tests performed after pre-conditioning test (PC)

Further abbreviations: MSL - moisture sensitivity level, Qty – quantity, RH – relative humidity, SS – sample size, Ta – ambient temperature, Ts – solder temperature

Trademarks
All referenced product or service names and trademarks are the property of their respective owners.

Edition 2016-01-22

Published by

Infineon Technologies AG

81726 München, Germany

© 2018 Infineon Technologies AG. All Rights Reserved.

Do you have a question about this document?

Email: erratum@infineon.com

Document reference

n.a.

IMPORTANT NOTICE

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

For further information on the product, technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies office (**www.infineon.com**).

WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.